

Preliminary Technical Data Sheet

Preface

ADMER™ AT3182E is a maleic anhydride grafted, PE-based adhesive designed for shrink-film in double bubble processes.

Properties

Item	Value	Unit	ASTM Testing Method
MFR (190°C, 2.16kg)	1.7	g/10 min	D1238
Density	0.903	g/cm ³	D1505
Tensile Strength at Yield	-	MPa	D638
Tensile Strength at Break	23	MPa	D638
Elongation at Break	> 500	%	D638
Izod Impact Strength	No Break	J/m ²	D256
Shore Hardness	39	D scale	D2240
Vicat Softening Point	69	°C	D1525



ADMER™ AT3182E

PE-Grade
MFR: 1.7
Density: 0.903

Processing

The recommended processing temperatures for ADMER™ can be found in our temperature proposal.

Maximum temperature: 300 °C; Temperatures above the upper limit or long residence times of molten resin may lead to decomposition of the polymer. Decomposition products may be carbon monoxide, carbon dioxide, hydrocarbons and water.

Whilst the extrusion process is either interrupted or terminated:

Less than 2 hours: Screw rotation can be stopped maintaining temperature.

More than 2 hours: Purge out and shut down in accordance with common procedure.

Handling

ADMER™ resins are supplied in the form of small, free flowing pellets and can be easily handled with commercially available equipment. As long as ADMER™ is stored under good conditions, it does not require any special care in storage. Precaution should be taken in opening the package to avoid contamination by foreign materials.

Since ADMER™ is a non-hygroscopic material, it absorbs less moisture than non-polyolefin polymers. Therefore, ADMER™ does not require drying prior to processing.

ADMER™ can be disposed of by either landfill or incineration. However, any disposal must comply with local regulations and recommendations.

Disclaimer:

The information and numerical results are for information only and are given in good faith.

In view of numerous factors of which we are unaware and which are beyond our control regarding the use of our products, we cannot guarantee that this information covers all possible aspects of the subject. Moreover, we cannot accept any responsibility with regard to patents for applications and processes described.